

**IN THE DRAWINGS:**

The attached sheet of drawings includes a change to FIG. 12A. This sheet, which includes FIG. 12A, replaces the original sheet including FIG. 12A.

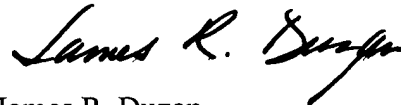
**REMARKS**

No new matter has been added. The amendments to the claims address typographical and spelling errors, and improve antecedent basis. The amendments do not affect, or surrender, any scope of any claim as originally filed.

FIG. 12A has been amended herein. Specifically, FIG. 12A has been revised to change the wording in box #6 to read "ETCH WAFER 10 TO REMOVE PORTIONS OF WAFER 10 IN STREET AREAS 22 BETWEEN SEMICONDUCTOR CHIPS 12 UNTIL REACH GLASS LAYER 30." No new matter has been added.

The Applicants again request entry of the amendments as set forth herein prior to examination of the application on the merits.

Respectfully submitted,



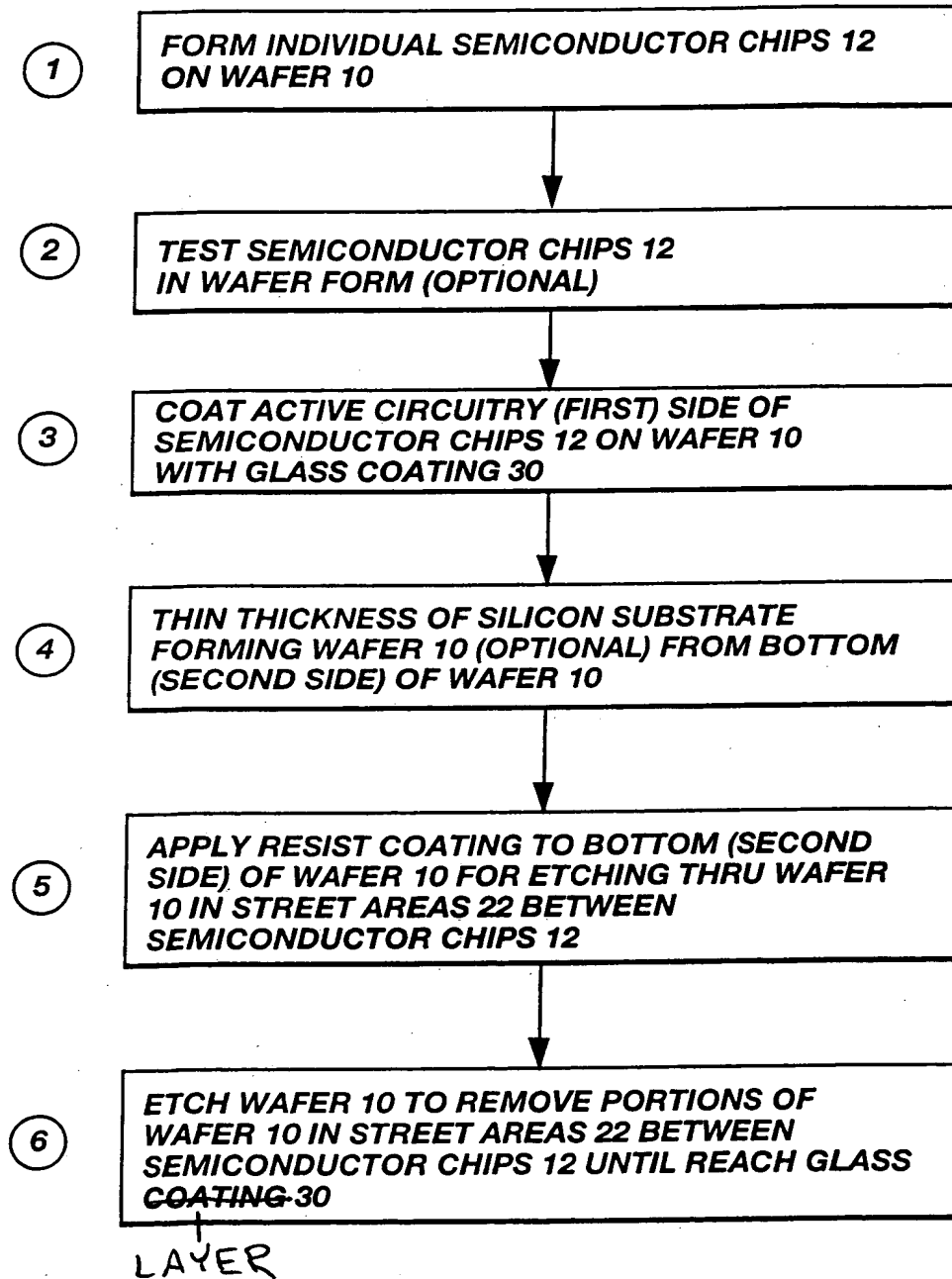
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JRD/tlb

Enclosures    Replacement Sheet  
                  Annotated Sheet Showing Changes

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**Fig. 12A**